



## Product/Process Change Notice - PCN 18\_0097 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

*Note: Revised fields are indicated by a red field name. See Appendix B for revision history.*

**PCN Title:** ADRF6821 Process Robustness Improvement and Die Revision

**Publication Date:** 03-Jul-2018

**Effectivity Date:** 05-Oct-2018 *(the earliest date that a customer could expect to receive changed material)*

### Revision Description:

Revised "description of change" for further clarification from "Added Down-Bond to ESD ground connections; Back-to-Back diodes" to "Added Back-to-Back diodes on down-bond pads."

### Description Of Change:

#### 1. Die Revision:

- Added ESD Domain connections between all grounds; Back-to-Back diodes
- Added Back-to-Back diodes on Down-Bond pads.
- Added up/down diodes between interconnected blocks.

#### 2. Electrical Specification:

- Device Identification through Register Readback is change:
- ADI Engineering Register 0x0010 value from 0x20 to 0x30
- ADI Engineering Register 0x1010 value from 0x20 to 0x34

### Reason For Change:

1. Process Robustness Improvement.
2. Increased production to meet customers demand.

### Impact of the change (positive or negative) on fit, form, function & reliability:

-No change to fit, form, function & reliability.

### Product Identification *(this section will describe how to identify the changed material)*

Device Identification through Register Readback.

### Summary of Supporting Information:

Qualification will be performed per Industry Standard Test Methods. See attached Qualification Plan.

### Supporting Documents

**Attachment 1: Type:** Qualification Plan

ADI\_PCN\_18\_0097\_Rev\_A\_ADRF6821\_Qualification\_Plan.pdf

**For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.**

**Americas:**  
PCN\_Americas@analog.com

**Europe:**  
PCN\_Europe@analog.com

**Japan:**  
PCN\_Japan@analog.com

**Rest of Asia:**  
PCN\_ROA@analog.com

**Appendix A - Affected ADI Models**

**Existing Parts - Product Family / Model Number (3)**

ADRF6821 / ADRF6821ACPZ

ADRF6821 / ADRF6821ACPZ-RL7

ADRF6821 / ADRF6821XCPZ

**Appendix B - Revision History**

<b>Rev</b>	<b>Publish Date</b>	<b>Effectivity Date</b>	<b>Rev Description</b>
Rev. -	20-Jun-2018	22-Sep-2018	Initial Release.
Rev. A	03-Jul-2018	05-Oct-2018	Revised "description of change" for further clarification from "Added Down-Bond to ESD ground connections; Back-to-Back diodes" to "Added Back-to-Back diodes on down-bond pads."

Analog Devices, Inc.

DocId:4471 Parent DocId:None Layout Rev:7